

IGBT - Ultra Field Stop

NGTB40N120L3WG

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Ultra Field Stop Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for motor driver applications. Incorporated into the device is a soft and fast co-packaged free wheeling diode with a low forward voltage.

Features

- Extremely Efficient Trench with Field Stop Technology
- $T_{Jmax} = 175^{\circ}C$
- Soft Fast Reverse Recovery Diode
- Optimized for Low V_{CEsat}
- These are Pb-Free Devices

Typical Applications

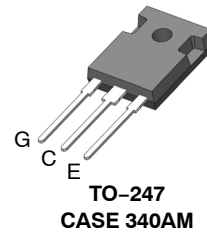
- Solar Inverter and UPS
- Industrial Switching
- Welding

ABSOLUTE MAXIMUM RATINGS

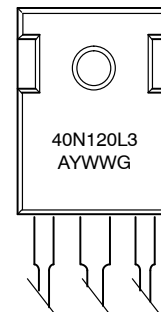
| Rating | Symbol | Value | Unit |
|---|-----------|----------------------|-------------|
| Collector-emitter Voltage | V_{CES} | 1200 | V |
| Collector Current @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$ | I_C | 160 40 | A |
| Pulsed Collector Current, T_{pulse} Limited by T_{Jmax} | I_{CM} | 160 | A |
| Diode Forward Current @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$ | I_F | 160 40 | A |
| Diode Pulsed Current, T_{pulse} Limited by T_{Jmax} | I_{FM} | 160 | A |
| Gate-emitter Voltage Transient Gate-emitter Voltage ($t_{pulse} = 5 \mu s, D < 0.10$) | V_{GE} | ± 20 ± 30 | V |
| Power Dissipation @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$ | P_D | 454 227 | W |
| Operating Junction Temperature Range | T_J | -55 to +175 | $^{\circ}C$ |
| Storage Temperature Range | T_{stg} | -55 to +175 | $^{\circ}C$ |
| Lead temperature for soldering, 1/8" from case for 5 seconds | T_{SLD} | 260 | $^{\circ}C$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

40 A, 1200 V
 $V_{CEsat} = 1.55 V$
 $E_{off} = 1.5 mJ$



MARKING DIAGRAM



40N120L3 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

| Device | Package | Shipping |
|----------------|---------------------|-----------------|
| NGTB40N120L3WG | TO-247 (Pb-Free) | 30 Units / Rail |

NGTB40N120L3WG

THERMAL CHARACTERISTICS

| Rating | Symbol | Value | Unit |
|--|-----------------|-------|-----------------------------|
| Thermal resistance junction-to-case, for IGBT | $R_{\theta JC}$ | 0.33 | $^{\circ}\text{C}/\text{W}$ |
| Thermal resistance junction-to-case, for Diode | $R_{\theta JC}$ | 0.61 | $^{\circ}\text{C}/\text{W}$ |
| Thermal resistance junction-to-ambient | $R_{\theta JA}$ | 40 | $^{\circ}\text{C}/\text{W}$ |

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise specified)

| Parameter | Test Conditions | Symbol | Min | Typ | Max | Unit |
|-----------|-----------------|--------|-----|-----|-----|------|
|-----------|-----------------|--------|-----|-----|-----|------|

STATIC CHARACTERISTIC

| | | | | | | |
|---|---|---------------|------|-------------|----------|----|
| Collector-emitter breakdown voltage, gate-emitter short-circuited | $V_{GE} = 0\text{ V}, I_C = 500\ \mu\text{A}$ | $V_{(BR)CES}$ | 1200 | - | - | V |
| Collector-emitter saturation voltage | $V_{GE} = 15\text{ V}, I_C = 40\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 40\text{ A}, T_J = 175^{\circ}\text{C}$ | V_{CEsat} | - | 1.55 2.0 | 1.8 - | V |
| Gate-emitter threshold voltage | $V_{GE} = V_{CE}, I_C = 400\ \mu\text{A}$ | $V_{GE(th)}$ | 4.5 | 5.5 | 6.5 | V |
| Collector-emitter cut-off current, gate-emitter short-circuited | $V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}$ $V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}, T_J = 175^{\circ}\text{C}$ | I_{CES} | - | - 0.5 | 0.4 | mA |
| Gate leakage current, collector-emitter short-circuited | $V_{GE} = 20\text{ V}, V_{CE} = 0\text{ V}$ | I_{GES} | - | - | 200 | nA |

DYNAMIC CHARACTERISTIC

| | | | | | | |
|------------------------------|--|-----------|---|------|---|----|
| Input capacitance | $V_{CE} = 20\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$ | C_{ies} | - | 4912 | - | pF |
| Output capacitance | | C_{oes} | - | 140 | - | |
| Reverse transfer capacitance | | C_{res} | - | 80 | - | |
| Gate charge total | $V_{CE} = 600\text{ V}, I_C = 40\text{ A}, V_{GE} = 15\text{ V}$ | Q_g | - | 220 | - | nC |
| Gate to emitter charge | | Q_{ge} | - | 42 | - | |
| Gate to collector charge | | Q_{gc} | - | 110 | - | |

SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

| | | | | | | | |
|-------------------------|---|--------------|-------|-----|-----|----|----|
| Turn-on delay time | $T_J = 25^{\circ}\text{C}$ $V_{CC} = 600\text{ V}, I_C = 40\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 15\text{ V}$ | $t_{d(on)}$ | - | 18 | - | ns | |
| Rise time | | t_r | - | 30 | - | | |
| Turn-off delay time | | $t_{d(off)}$ | - | 150 | - | | |
| Fall time | | | t_f | - | 131 | - | mJ |
| Turn-on switching loss | | E_{on} | - | 1.5 | - | | |
| Turn-off switching loss | | E_{off} | - | 1.5 | - | | |
| Total switching loss | | E_{ts} | - | 3.0 | - | | |
| Turn-on delay time | $T_J = 175^{\circ}\text{C}$ $V_{CC} = 600\text{ V}, I_C = 40\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 15\text{ V}$ | $t_{d(on)}$ | - | 18 | - | ns | |
| Rise time | | t_r | - | 31 | - | | |
| Turn-off delay time | | $t_{d(off)}$ | - | 156 | - | | |
| Fall time | | | t_f | - | 220 | - | mJ |
| Turn-on switching loss | | E_{on} | - | 2.0 | - | | |
| Turn-off switching loss | | E_{off} | - | 2.3 | - | | |
| Total switching loss | | E_{ts} | - | 4.3 | - | | |

DIODE CHARACTERISTICS

| | | | | | | |
|--|---|---------------|---|------------|----------|------------------|
| Forward voltage | $V_{GE} = 0\text{ V}, I_F = 40\text{ A}$ $V_{GE} = 0\text{ V}, I_F = 40\text{ A}, T_J = 175^{\circ}\text{C}$ | V_F | - | 3.0 2.8 | 3.4 - | V |
| Reverse recovery time | $T_J = 25^{\circ}\text{C}$ $I_F = 40\text{ A}, V_R = 600\text{ V}$ $di_F/dt = 500\text{ A}/\mu\text{s}$ | t_{rr} | - | 86 | - | ns |
| Reverse recovery charge | | Q_{rr} | - | 0.56 | - | μC |
| Reverse recovery current | | I_{rrm} | - | 12 | - | A |
| Diode peak rate of fall of reverse recovery current during t_b | | di_{rrm}/dt | - | -210 | - | A/ μs |

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Test Conditions | Symbol | Min | Typ | Max | Unit |
|--|---|---------------|-----|------|-----|------------------------|
| DIODE CHARACTERISTICS | | | | | | |
| Reverse recovery time | $T_J = 125^\circ\text{C}$ $I_F = 40\text{ A}$, $V_R = 600\text{ V}$ $di_F/dt = 500\text{ A}/\mu\text{s}$ | t_{rr} | – | 136 | – | ns |
| Reverse recovery charge | | Q_{rr} | – | 1.47 | – | μC |
| Reverse recovery current | | I_{rrm} | – | 20 | – | A |
| Diode peak rate of fall of reverse recovery current during t_b | | dI_{rrm}/dt | – | –212 | – | $\text{A}/\mu\text{s}$ |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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TYPICAL CHARACTERISTICS

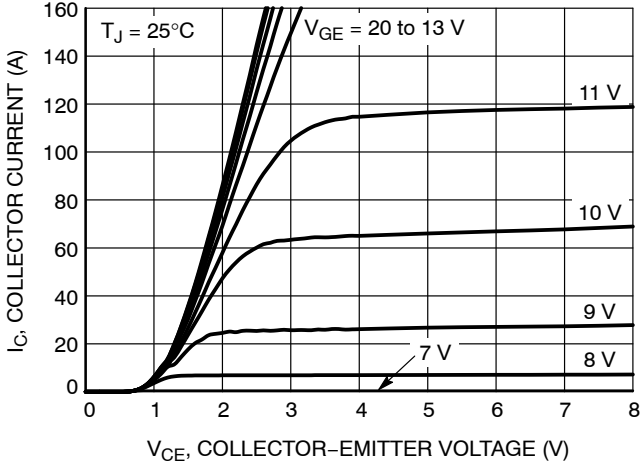


Figure 1. Output Characteristics

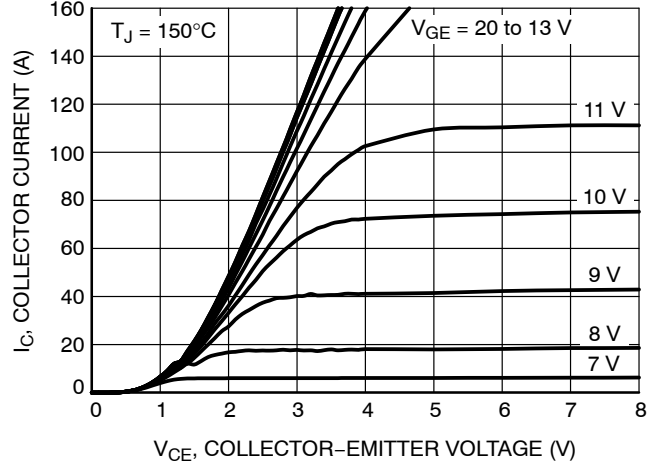


Figure 2. Output Characteristics

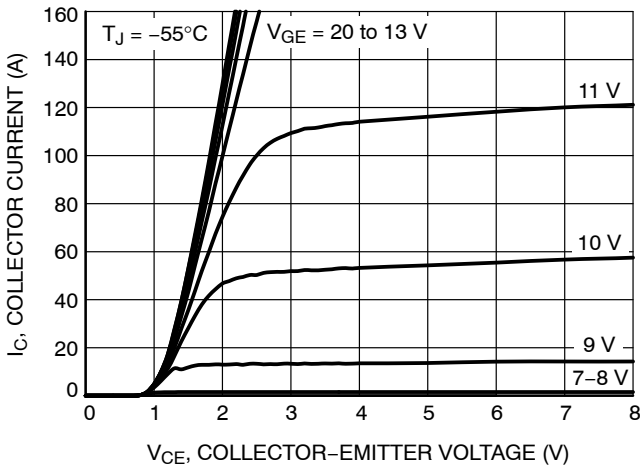


Figure 3. Output Characteristics

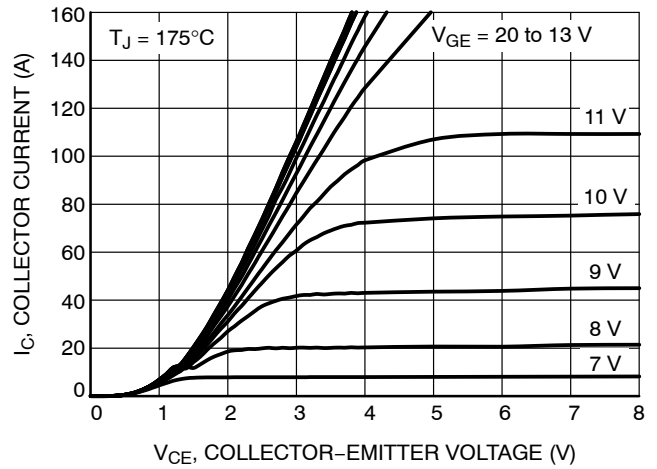


Figure 4. Output Characteristics

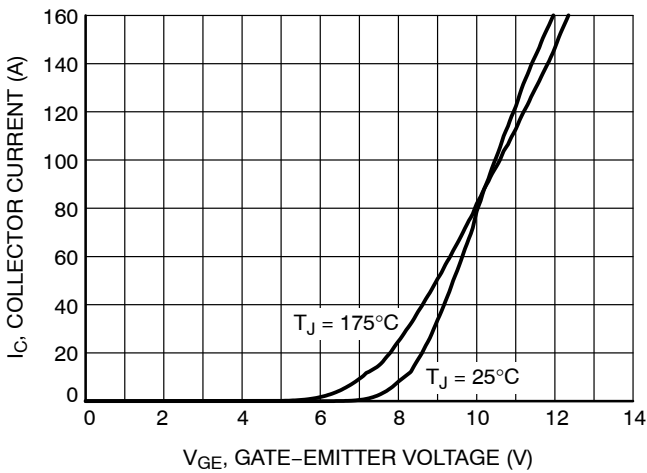


Figure 5. Typical Transfer Characteristics

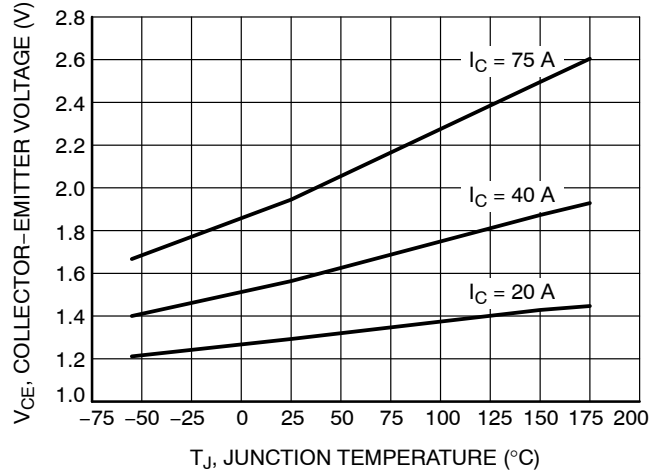


Figure 6. $V_{CE(sat)}$ vs. T_J

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TYPICAL CHARACTERISTICS

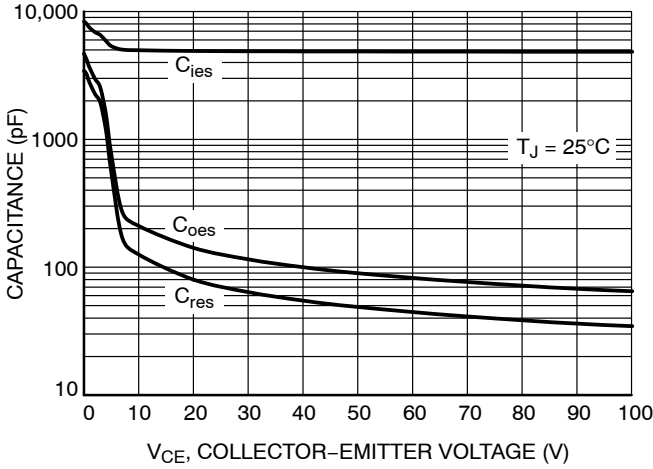


Figure 7. Typical Capacitance

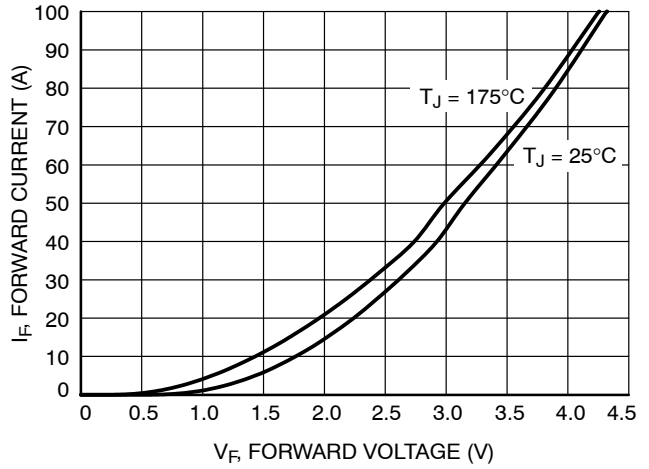


Figure 8. Diode Forward Characteristics

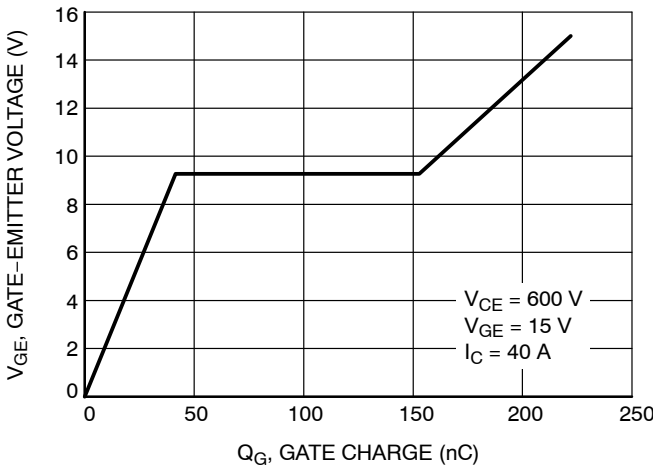


Figure 9. Typical Gate Charge

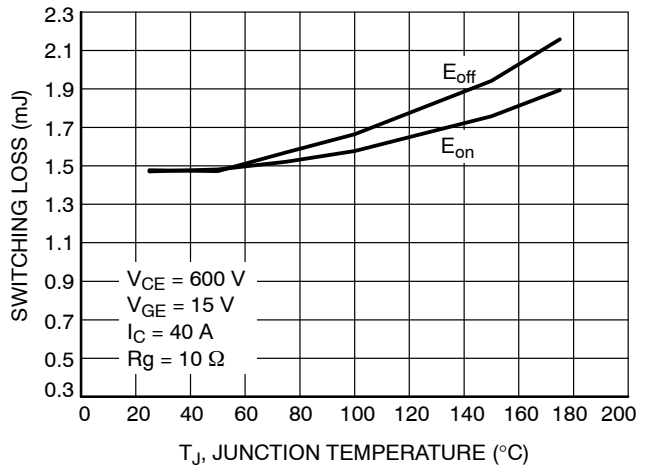


Figure 10. Switching Loss vs. Temperature

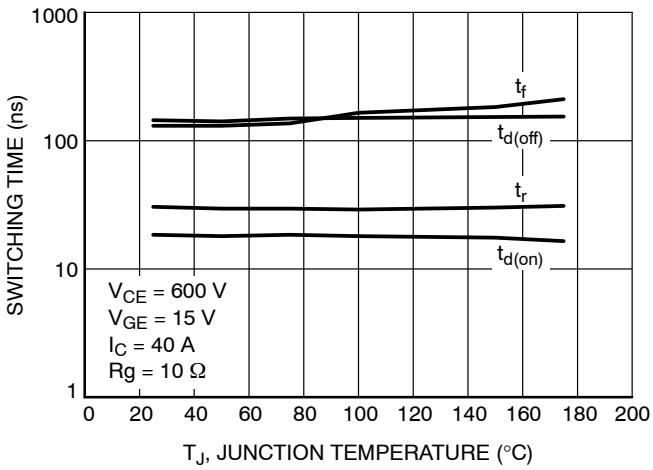


Figure 11. Switching Loss vs. Temperature

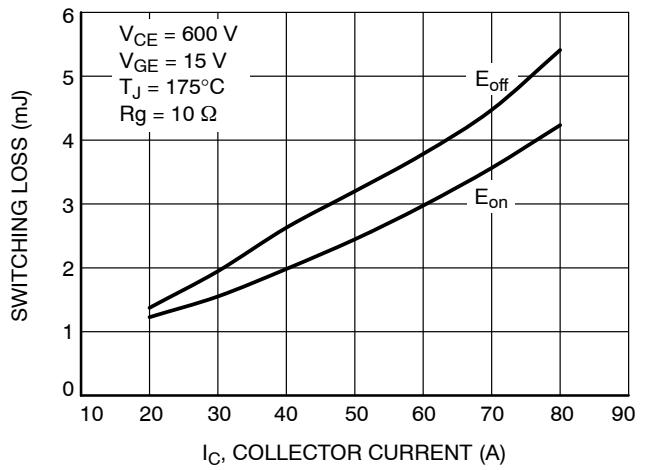


Figure 12. Switching Loss vs. I_C

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TYPICAL CHARACTERISTICS

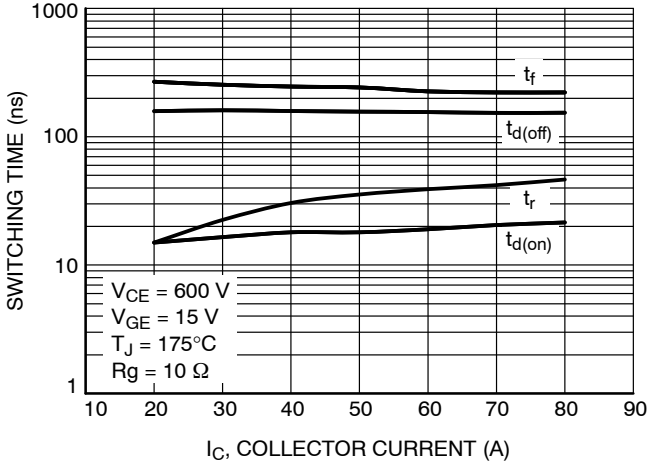


Figure 13. Switching Time vs. I_C

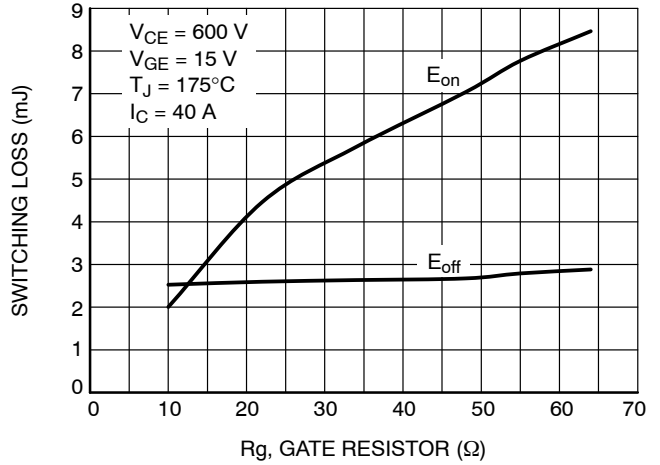


Figure 14. Switching Loss vs. R_g

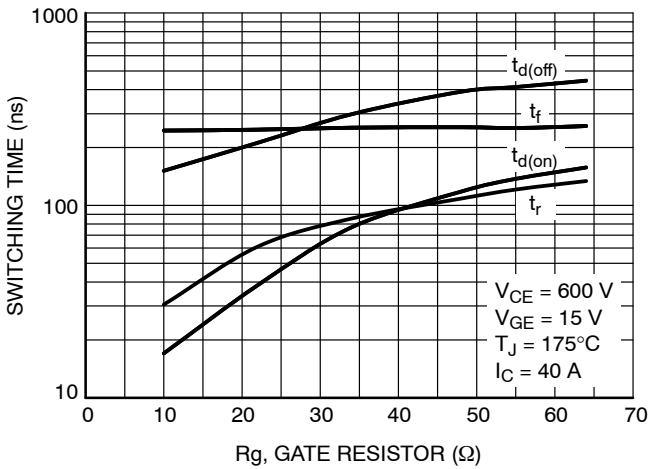


Figure 15. Switching Time vs. R_g

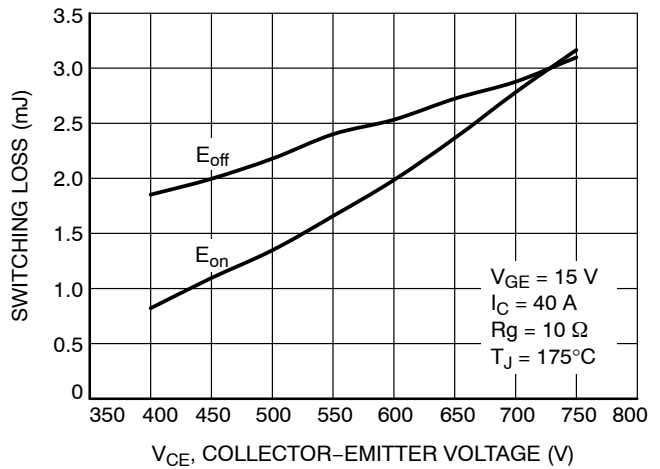


Figure 16. Switching Loss vs. V_{CE}

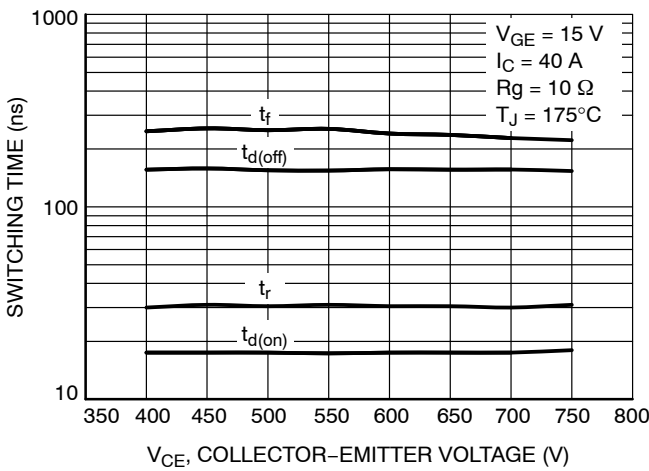


Figure 17. Switching Time vs. V_{CE}

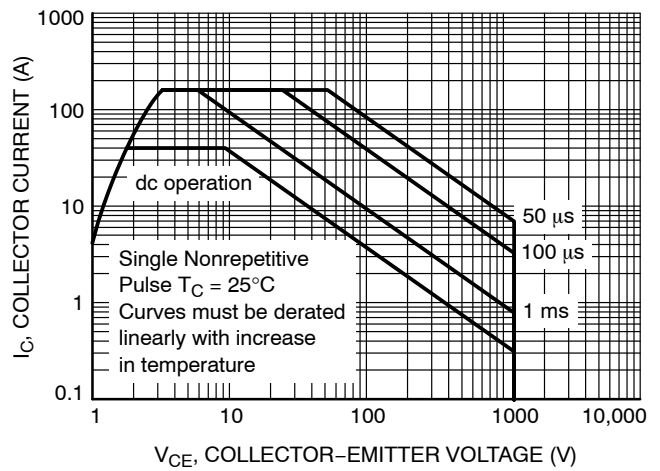


Figure 18. Safe Operating Area

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TYPICAL CHARACTERISTICS

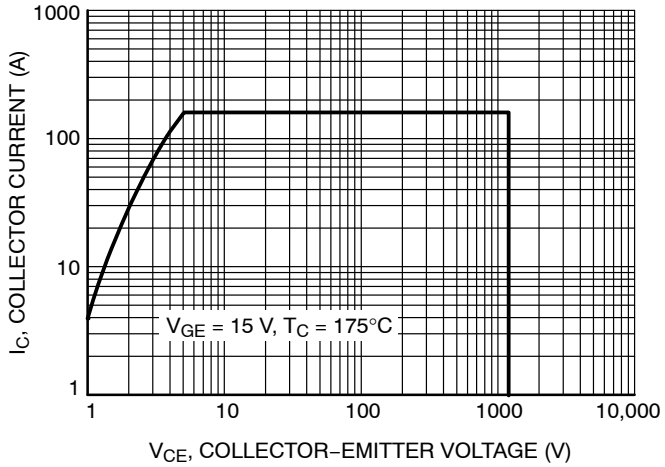


Figure 19. Reverse Bias Safe Operating Area

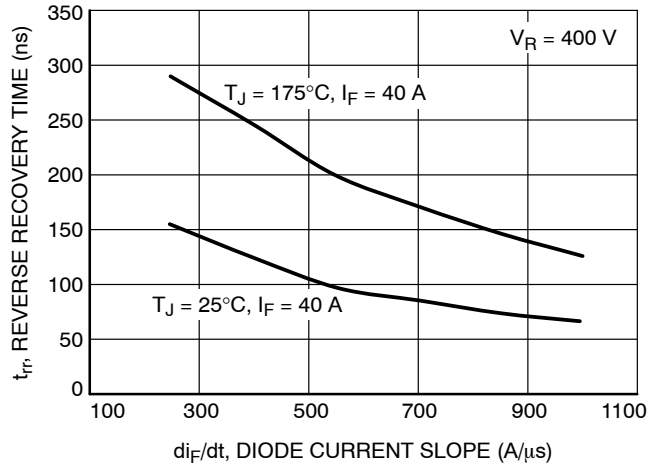


Figure 20. t_{rr} vs. di_F/dt

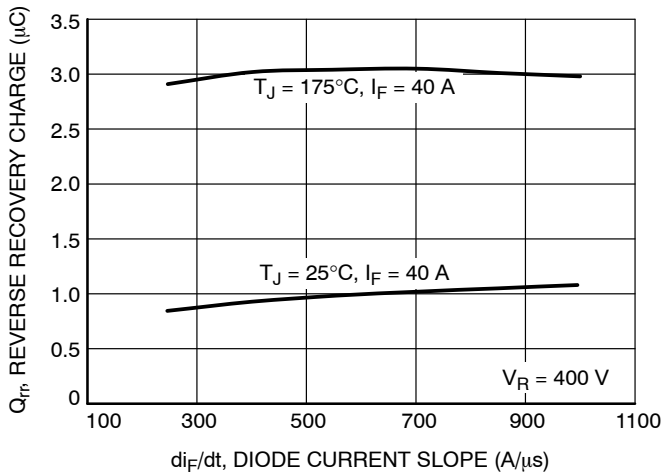


Figure 21. Q_{rr} vs. di_F/dt

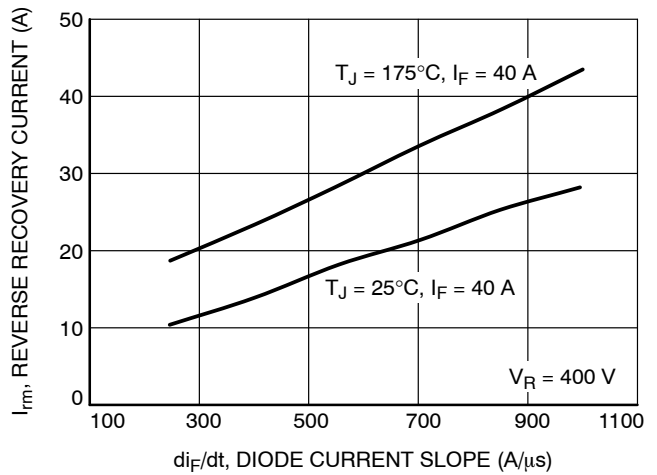


Figure 22. I_{rm} vs. di_F/dt

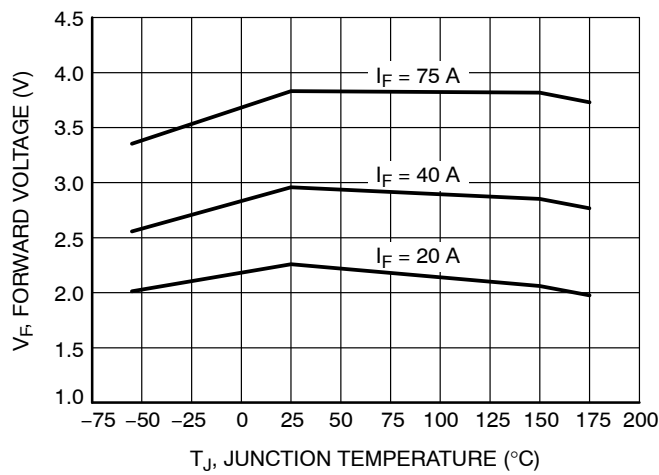


Figure 23. V_F vs. T_J

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TYPICAL CHARACTERISTICS

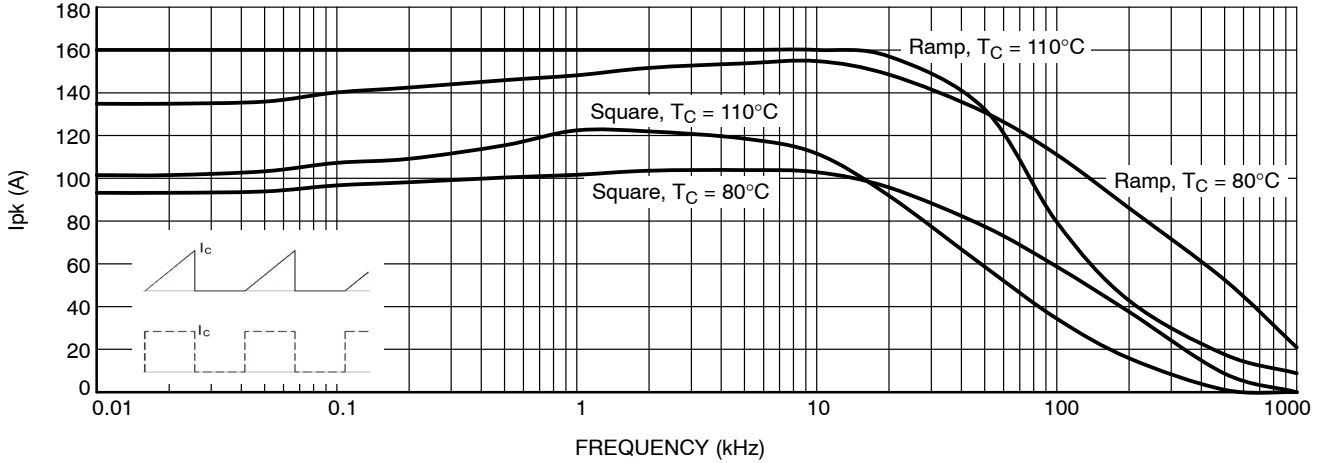


Figure 24. Collector Current vs. Switching Frequency

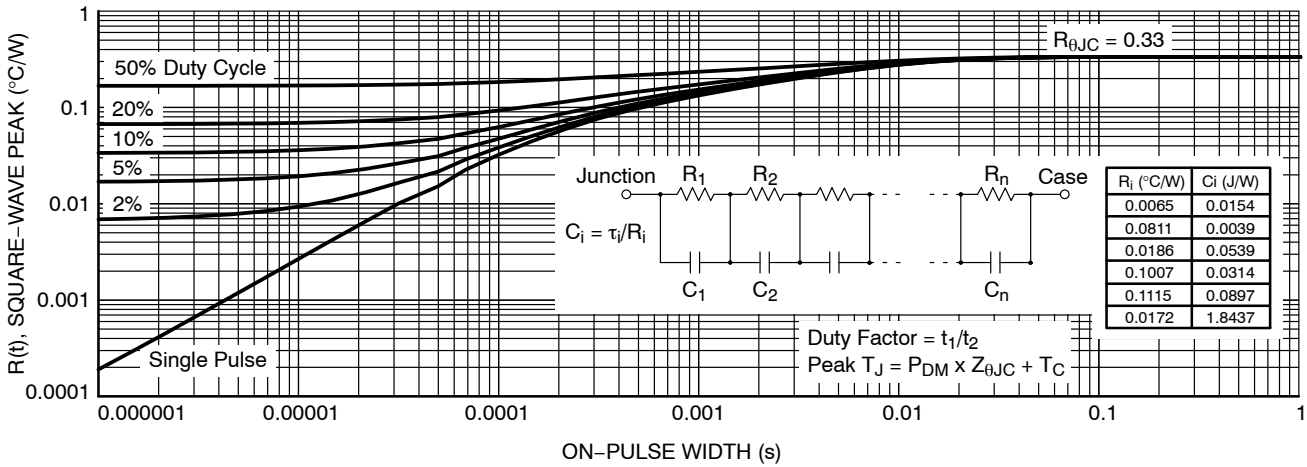


Figure 25. IGBT Transient Thermal Impedance

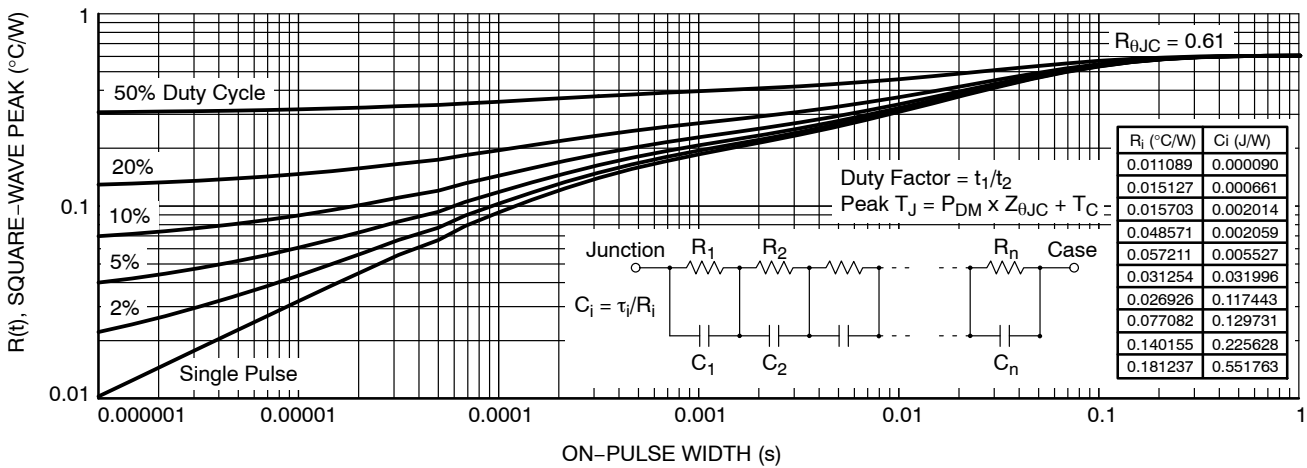


Figure 26. Diode Transient Thermal Impedance

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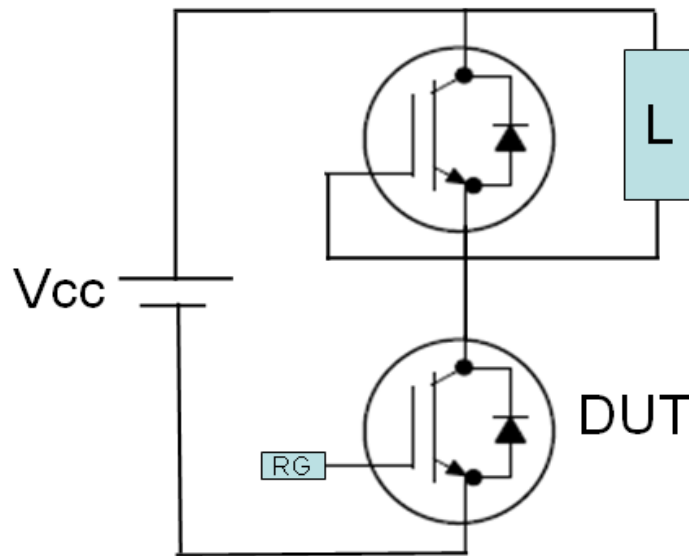


Figure 27. Test Circuit for Switching Characteristics

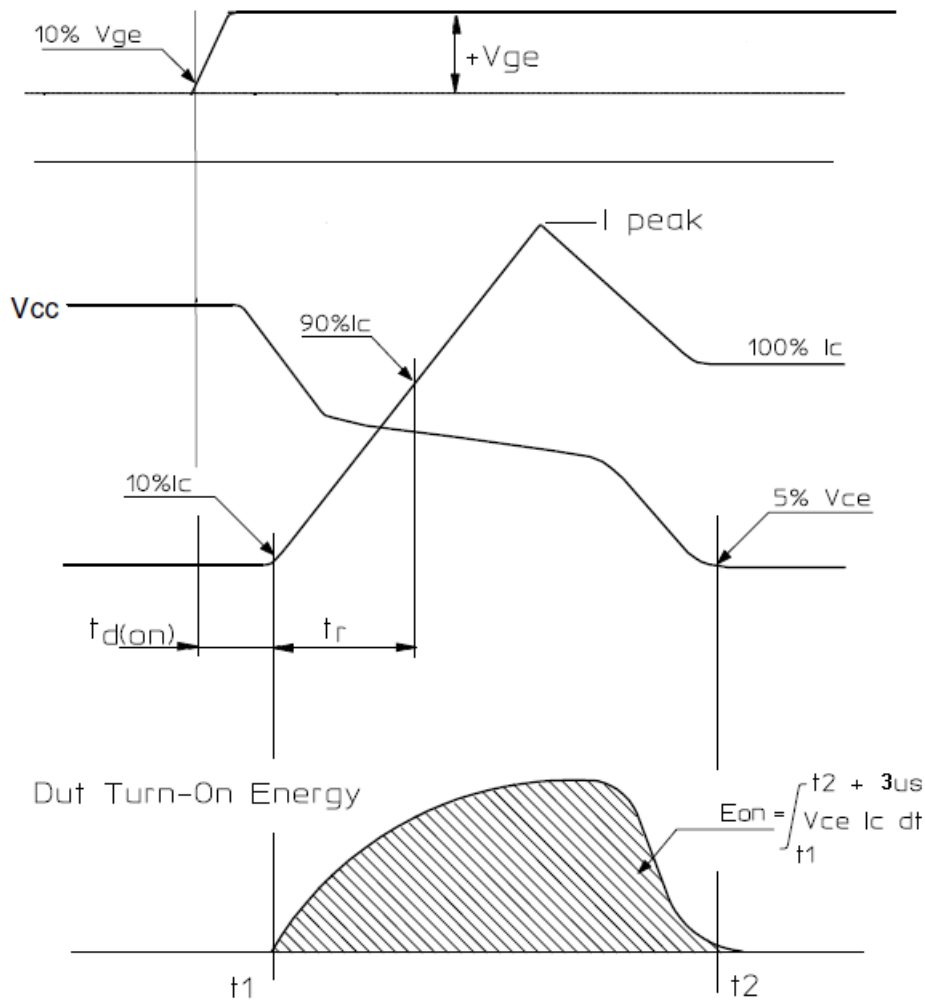


Figure 28. Definition of Turn On Waveform

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Figure 29. Definition of Turn Off Waveform

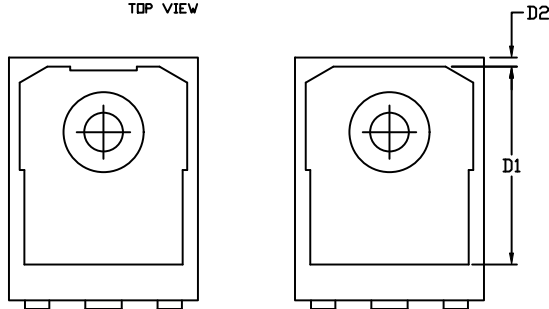
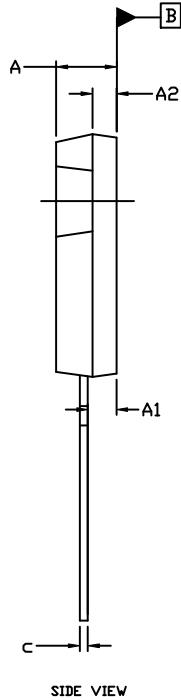
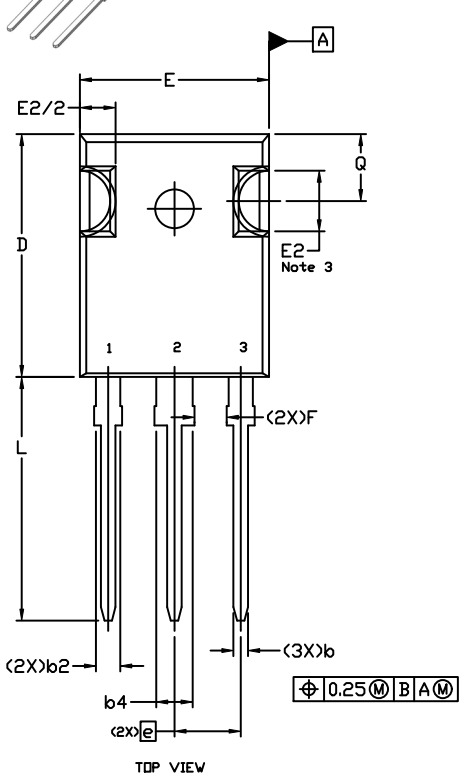
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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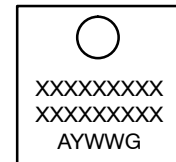
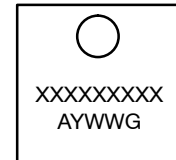
NOTE 4 HEATSINK SHAPES

NOTES:

1. DIMENSIONING AND TOLERANCE AS PER ASME Y14.5M, 2009.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. SLOT REQUIRED, NOTCH MAY BE ROUNDED.
4. OPTIONAL BACK SIDE HEATSINK SHAPE.
5. DIMENSIONS ARE EXCLUSIVE OF BURRS AND MOLD FLASH. DIMENSIONS D AND E ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
6. DIMENSIONS A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
7. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

| DIM | MILLIMETERS | | |
|-----|-------------|-------|-------|
| | MIN | NOM | MAX |
| A | 4.70 | 5.00 | 5.30 |
| A1 | 2.20 | 2.40 | 2.60 |
| A2 | 1.80 | 2.00 | 2.20 |
| b | 1.07 | 1.20 | 1.33 |
| b2 | 1.65 | 2.12 | 2.35 |
| b4 | 2.60 | 3.12 | 3.40 |
| c | 0.45 | 0.60 | 0.75 |
| D | 20.80 | 21.00 | 21.34 |
| D1 | 16.30 | --- | --- |
| D2 | 0.75 | --- | --- |
| E | 15.50 | 16.00 | 16.25 |
| E1 | 13.80 | --- | --- |
| E2 | 4.32 | 4.90 | 5.49 |
| e | 5.45 BSC | | |
| F | 2.655 | --- | --- |
| L | 19.80 | 20.00 | 20.80 |
| L1 | 3.81 | 4.20 | 4.35 |
| P | 3.55 | 3.60 | 3.65 |
| P1 | 6.60 | --- | --- |
| Q | 5.40 | 6.00 | 6.20 |
| S | 6.15 BSC | | |

GENERIC MARKING DIAGRAMS*



XXXX = Specific Device Code
 A = Assembly Location
 Y = Year
 WW = Work Week
 G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

| | | |
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